**Board Characteristics**

1. All dimensions are given in inches unless specified otherwise.
2. Material FR4
3. Minimum trace width and clearance: 0.007
4. 1 oz copper for all power layers and for Signal_1,2 (Top and Bottom)
5. Immersion Gold over copper, with min. Ni: 2.5-5 um, Au: 0.05-0.2 um
   - Apply Solder Mask over bare copper
6. Board Thickness: 0.063 +/- 0.008
7. Silk-screen on Component and Solder Sides
8. FHS tolerances: +/- 0.003 unless specified otherwise
9. Interlayer spacing as specified
10. Tolerance: 4/- 0.003 unless specified otherwise

**Board's Drill Schedule**

<table>
<thead>
<tr>
<th>DRILL SYMBOL</th>
<th>DRILL SIZE</th>
<th>COUNT</th>
<th>PLATED</th>
<th>TOLERANCE</th>
<th>COMMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>.02</td>
<td>7</td>
<td>YES</td>
<td>---</td>
<td></td>
</tr>
<tr>
<td>B</td>
<td>.035</td>
<td>6</td>
<td>YES</td>
<td>---</td>
<td></td>
</tr>
</tbody>
</table>

**Layer Order**

- Signal 1
- Power

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**Microstrip Board Characteristics**

- University of Chicago
- Electronics Development Group
- PMT PreAmp
- Specification Drawing
- 2851 A
- M. Bogdan
- M. Bogdan